



6AU-2841

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant: Brad D. Rumsey

§ Art Unit: 2841

Serial No.: 09/377,286

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Examiner: K. Cuneo

Docket No. MICT-0050-US
(99-0325)

#6/Amend A

R. Tyson

6/4/01

RECEIVED
MAY 31 2001
TECHNOLOGY CENTER 2800Commissioner for Patents
Washington, D.C. 20231**REPLY TO PAPER NO. 5**

Sir:

6/4/01
✓

This paper is submitted in response to the Office Action dated March 14, 2001 for which the shortened-statutory period for response is set to expire on June 14, 2001. The Applicant respectfully requests that the Examiner make amendments to the above referenced application as follows:

In the Claims

Please amend claim 1 as follows:

- A
- 1 1. (Amended) A bond pad assembly comprising:
 - 2 a bond pad;
 - 3 a trace that applies an attractive force to solder placed on
 - 4 the pad, said trace coupled to said pad and extending away from said pad in a
 - 5 first direction; and

Date of Deposit: 5/21/01
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington, DC 20231.
Sharon V. Hart
Sharon V. Hart